

OL-TDA19988AU

Bare die; 84 bond pads

10 February 2016

Package information

1. Package summary

Terminal position code	U (upper)
Package type descriptive code	UC
Package type industry code	UC
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	13-4-2011

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		[tbd]	-	2.856	[tbd]	mm
E	package width		[tbd]	-	2.856	[tbd]	mm
A	seated height		[tbd]	-	0.738	[tbd]	mm
A ₂	package height		[tbd]	-	0.725	[tbd]	mm
e	nominal pitch		-	-	0.08	-	mm
n ₂	actual quantity of termination		-	-	84	-	



2. Package outline

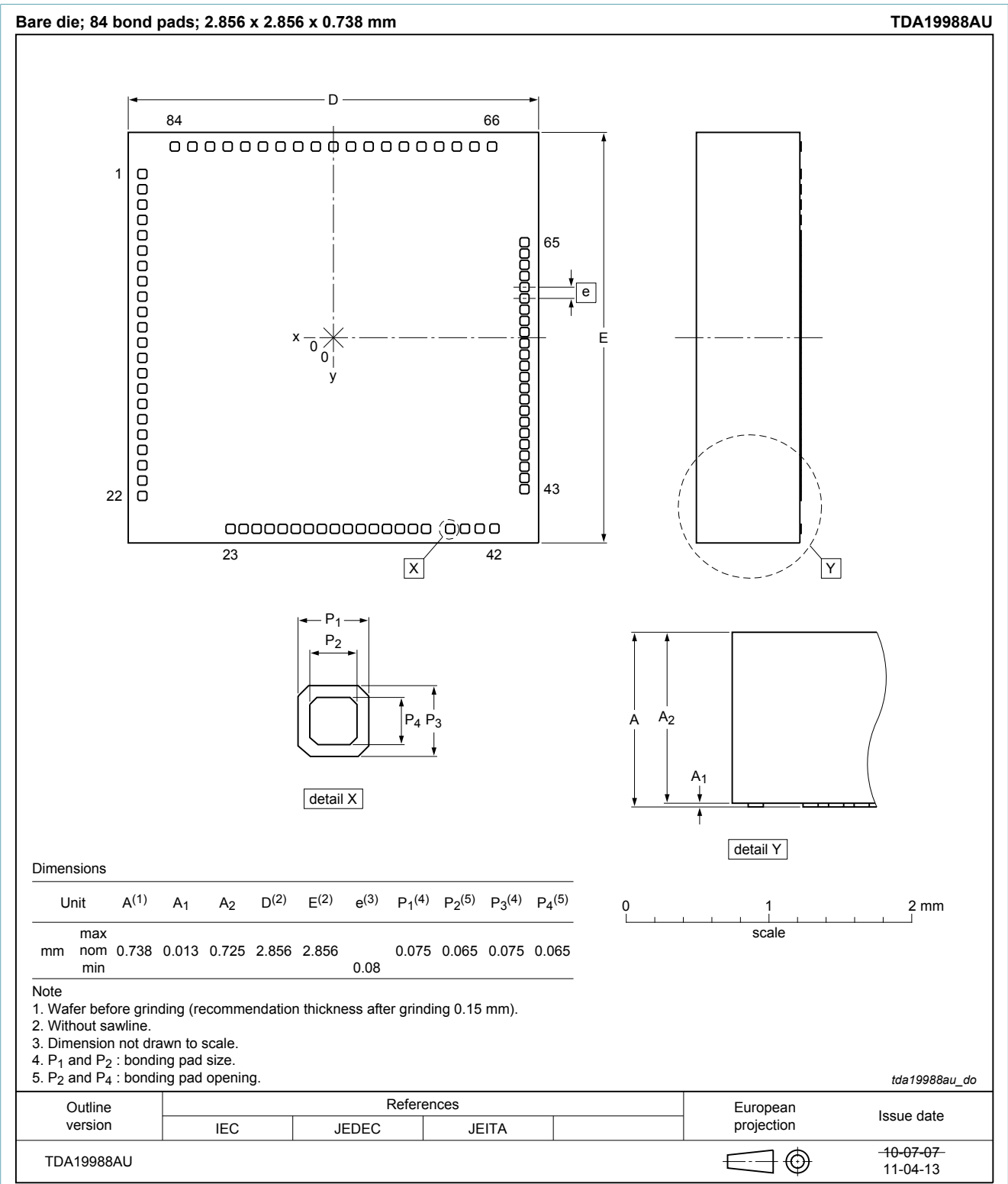


Fig. 1. Package outline UC (OL-TDA19988AU)

3. Legal information

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